



Product Change Notification - RMES-20MUIN990

Date:

05 Jun 2020

Product Category:

USB Bridge; USB Hubs

Affected CPNs:**Notification subject:**

CCB 4199 Final Notice: Qualification of ASE as a new assembly site for USB2660I-JZX-03, USB2660I-JZX-03-TR and USB2517-JZX-AC0 catalog part numbers (CPN) available in 64L QFN package.

Notification text:**PCN Status:**

Final notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of ASE as a new assembly site for USB2660I-JZX-03, USB2660I-JZX-03-TR and USB2517-JZX-AC0 catalog part numbers (CPN) available in 64L QFN package.

Pre Change:

Assembled at STATS Chippac Ltd. (STA) site using gold (Au) bond wire, 8290 die attach and G700 molding compound material

Post Change:

Assembled at ASE Inc. (ASE) site using gold (CuPdAu) bond wire, EN4900F die attach and G631 molding compound material

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	STATS Chippac Ltd. (STA)	ASE Inc. (ASE)
Wire material	Au	CuPdAu
Die attach material	8290	EN4900F
Molding compound material	G700	G631
Lead frame material	C194	C194

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve on-time delivery performance by qualifying ASE as a new assembly site.

Change Implementation Status:



In Progress

Estimated First Ship Date:

May 15, 2020 (date code: 2020)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	April 2020					May 2020				
Workweek	14	15	16	17	18	19	20	21	22	23
Qual Report Availability				X						
Final PCN Issue Date				X						
Estimated Implementation Date							X			

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:

April 21, 2020: Issued final notification. Attached is the qualification report and added the estimated first date by May 15, 2020.

June 05, 2020: Re-issued final notification to correct the package thickness information from 0.655mm to 0.9 mm in qualification report. Corrected the assembly site from STATS ChipPac (SCM) to STATS Chippac Ltd. (STA).

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN_RMES-20MUIN990_Qual_Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our [PCN home page](#) select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the [PCN FAQ](#) section.

If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.